

INTEGRATED CIRCUIT PACKAGE AND PRINTED CIRCUIT BOARD ARRANGEMENT

Abstract of Disclosure

An integrated circuit package device (100, 200, 300) has a plurality of contact points including an inner portion of contact points (120) and an outer portion of contact points (110). The integrated circuit package device includes at least one of the following: (i) one or more power supply contacts (130) configured substantially in said outer portion; (ii) one or more ground contacts (220, 230) configured substantially in said inner portion; (iii) one or more timing or frequency contacts (140) substantially in said outer portion; (iv) one or more data or high speed signal contacts (310) configured substantially in said outer portion of said integrated circuit package device. This provides the advantage that the required capacitors can be located as close to the power supply contacts as possible, and the tracking to these contacts can be kept to a minimum. Furthermore by providing the ground contacts toward the inner portion of the integrated circuit package device, the need for the other contacts to be routed around the ground contacts and any related vias is avoided.

Figures